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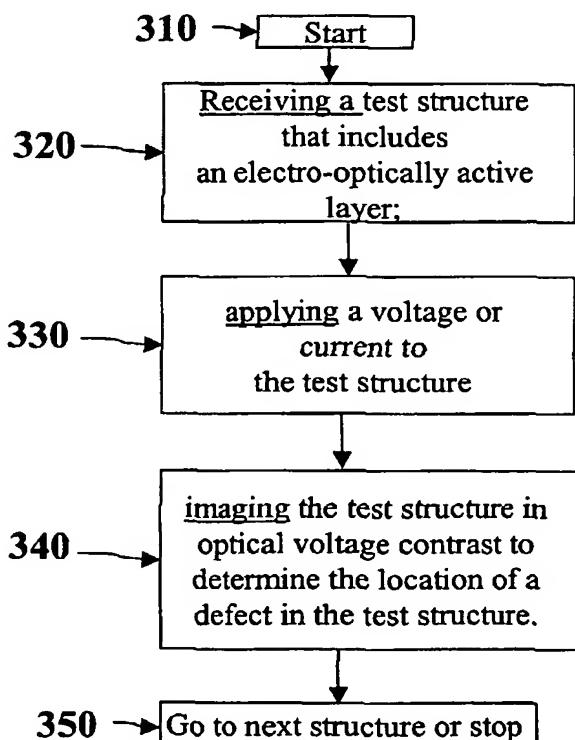
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(54) Title: SYSTEM AND METHOD FOR DEFECT LOCALIZATION



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(57) Abstract: A method and system for defect localization includes: (i) receiving a test structure that includes at least one conductor that is at least partially covered by an electro-optically active material; (ii) providing an electrical signal to the conductor, such as charge at least a portion of the conductor; and (iii) imaging the test structure to locate a defect.